

Title (en)

CONNECTING THERMALLY-SPRAYED LAYER STRUCTURES OF HEATING DEVICES

Title (de)

VERBINDEN THERMISCH AUFGESPRITZTER SCHICHTSTRUKTUREN VON HEIZEINRICHTUNGEN

Title (fr)

LIAISON THERMIQUE DE STRUCTURES DE COUCHES PULVÉRISÉES DE DISPOSITIFS DE CHAUFFAGE

Publication

**EP 3329737 A1 20180606 (DE)**

Application

**EP 16740977 A 20160701**

Priority

- DE 102015214627 A 20150731
- EP 2016065541 W 20160701

Abstract (en)

[origin: WO2017021076A1] The invention relates to a heating device (1) for a domestic appliance (H), comprising a planar carrier (2) with a carrier surface (3), at least one layer structure (4-8) that is thermally sprayed onto said carrier surface (3), and at least one solder volume (9, 13a, 13b, 17, 18, 19) that is applied to at least one thermally-sprayed layer structure (4-8), wherein at least one solder volume is an ultrasonically-soldered solder volume (9, 13a, 7, 19). A domestic appliance (H) with a heating device comprises at least one heating device (1). A method is used to produce a heating device (1) for a domestic appliance (H), wherein a planar carrier (2) is provided which has at least one thermally-sprayed layer structure (4-8) applied thereto, and at least one solder volume (9, 3a, 17, 19) is ultrasonically soldered onto at least one thermally-sprayed layer structure (4-8). The invention is particularly advantageous for use with cooking appliances, particularly those having steam cooking capabilities, dishwashers, washing machines, laundry care appliances and small domestic appliances.

IPC 8 full level

**H05B 3/22** (2006.01)

CPC (source: EP US)

**H05B 3/22** (2013.01 - EP US); **H05B 3/262** (2013.01 - US); **H05B 2203/013** (2013.01 - US); **H05B 2203/017** (2013.01 - US)

Citation (search report)

See references of WO 2017021076A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**DE 102015214627 A1 20170202**; CN 107926084 A 20180417; CN 107926084 B 20210727; EP 3329737 A1 20180606; EP 3329737 B1 20220413; PL 3329737 T3 20220725; US 11641698 B2 20230502; US 2018213607 A1 20180726; WO 2017021076 A1 20170209

DOCDB simple family (application)

**DE 102015214627 A 20150731**; CN 201680044726 A 20160701; EP 16740977 A 20160701; EP 2016065541 W 20160701; PL 16740977 T 20160701; US 201615747171 A 20160701